



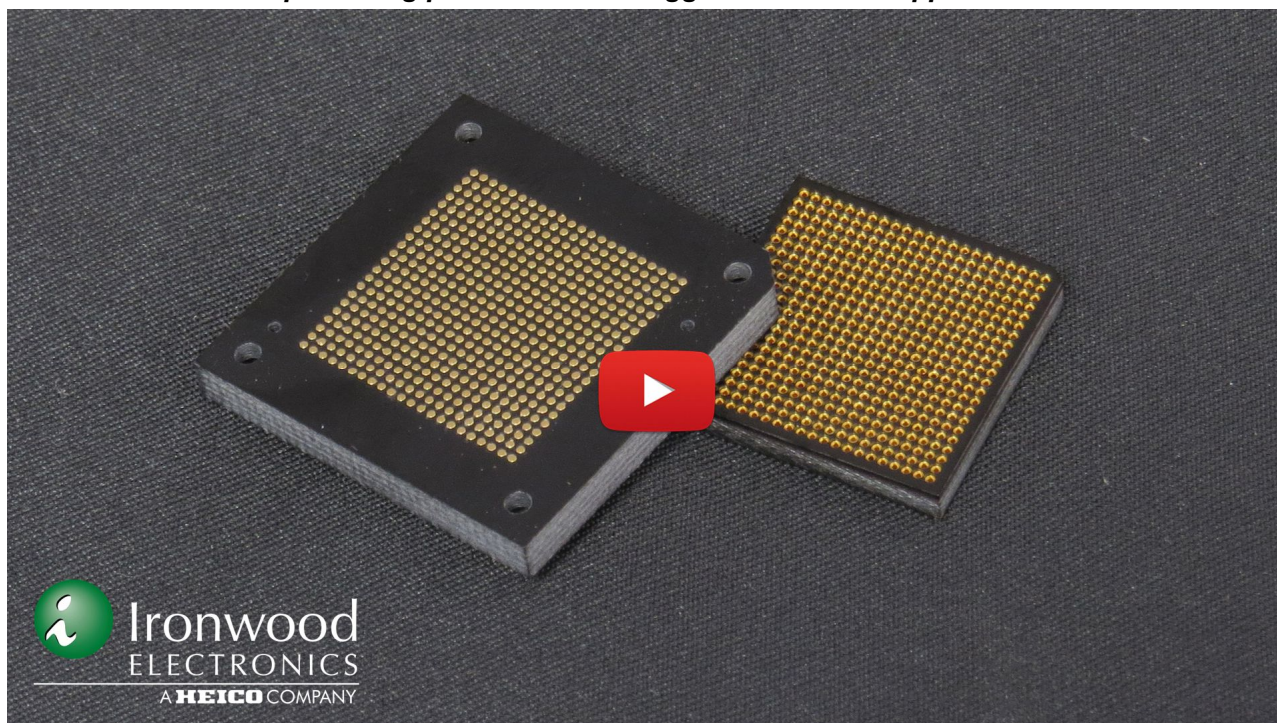
**Ironwood**  
ELECTRONICS



**High Performance  
Sockets & Adapters**

## Chip Size 0.8mm Pitch BGA Socket Adapter

**19x19mm body, 22X22 array 484 ball BGA package to be SMT attached to top adapter or placed inside compression mount socket mounted to top adapter. Bottom adapter attached to target PCB using reflow. Top and bottom adapters can be plugged/un-plugged multiple times and operated without compromising performance in rugged automotive applications.**



**Ironwood Electronics, Inc.** offers high performance test sockets and adapters for both engineering and production use of semiconductor devices. IC packages covered include QFN, BGA, SOIC, QFP, LGA, WLCSP and other SMT packages. Our GHz line of sockets with 6 different contact technologies supports up to 110 GHz bandwidth,  $\geq 0.2\text{mm}$  pitch,  $\leq 10000$  pins, 500K insertions and the smallest footprint in the industry !

## High Performance Sockets & Adapters

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